



Material Content Data Sheet



Sales Product Name		BSL316C H6327		Issued		25. January 2018		
MA#		MA001165086						
Package		PG-TSOP6-6-4		Weight*		14.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.006	0.04		437	
	noble metal	gold	7440-57-5	0.025	0.17		1696	
	inorganic material	silicon	7440-21-3	0.316	2.13	2.34	21347	23480
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		96	
	non noble metal	titanium	7440-32-6	0.007	0.05		478	
	non noble metal	chromium	7440-47-3	0.021	0.14		1433	
	non noble metal	copper	7440-50-8	7.048	47.59	47.79	475822	477829
wire	non noble metal	copper	7440-50-8	0.078	0.53	0.53	5260	5260
encapsulation	organic material	carbon black	1333-86-4	0.068	0.46		4569	
	plastics	epoxy resin	-	1.455	9.82		98233	
	inorganic material	silicondioxide	60676-86-0	5.245	35.41	45.69	354095	456897
leadfinish	non noble metal	tin	7440-31-5	0.392	2.65	2.65	26498	26498
plating	noble metal	silver	7440-22-4	0.149	1.00	1.00	10036	10036
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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